

Title (en)  
ELECTRICAL CONTACT ELEMENT AND METHOD FOR PRODUCING IT

Title (de)  
ELEKTRISCHES KONTAKTELEMENT UND VERFAHREN ZUR HERSTELLUNG EINES ELEKTRISCHEN KONTAKTELEMENTS

Title (fr)  
CONTACT ÉLECTRIQUE ET PROCÉDÉ POUR SA FABRICATION

Publication  
**EP 2524384 A1 20121121 (DE)**

Application  
**EP 11700420 A 20110114**

Priority  
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• EP 2011050482 W 20110114

Abstract (en)  
[origin: DE102010014745A1] The method involves providing a wire into a cladding, where wire is made of electrical conductive material e.g. copper. A cylindrical semi-finished material is formed by dividing the wire in a direction transverse to a wire longitudinal axis. The semi-finished material is fixed on a contact carrier (104) so that an electrical conductive material or metal coat of the cladding is connected with the carrier. The semi-finished material is reshaped for formation of a contact member (100). A contacting area (106) is accessible for a counter contact, via which the material of the wire is formed. An independent claim is also included for an electrical contact member that is manufactured by the method.

IPC 8 full level  
**H01H 1/021** (2006.01); **H01H 1/0237** (2006.01); **H01H 11/06** (2006.01)

CPC (source: EP US)  
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Citation (search report)  
See references of WO 2011086167A1

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